

# Si 800 $\mu$ m 1064nmAPD Chip

**P/N:YB-SIAPD800A1**

❖ **Applications**

Laser range finder,Laser alarming,RADAR,etc. application.

❖ **Absolute Maximum Rating**

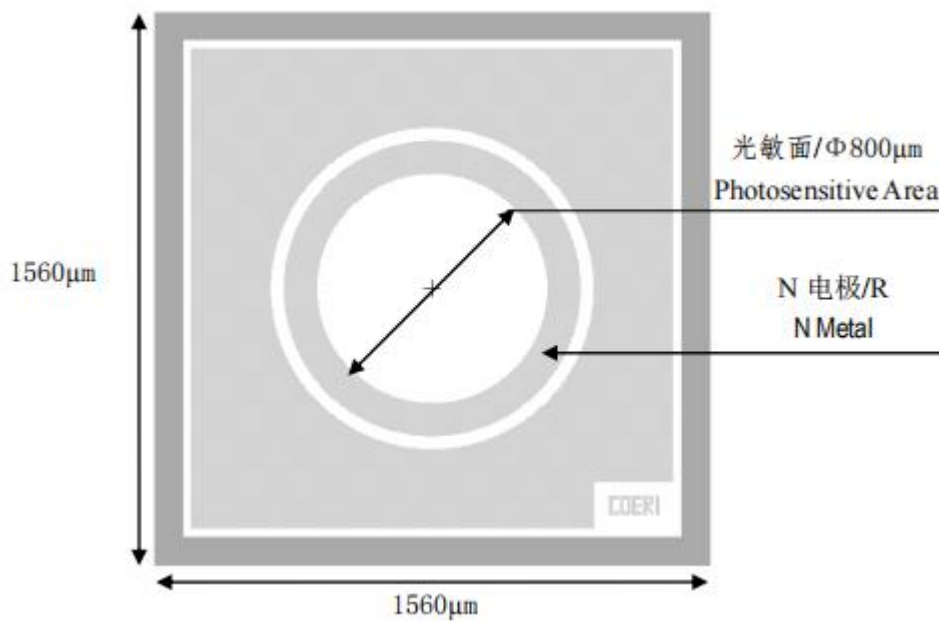
Parameter	Symbol	Min.	Max.	Unit
APD voltage supply	$V_{PD}$	—	$0.95 \cdot V_{BR}$	V
Operating Temperature	$T_C$	-45	+85	$^{\circ}C$
Storage Temperature	$T_{STG}$	-45	+100	$^{\circ}C$
Forward current	$I_F$	—	1	mA

❖ **Electro-Optical Characteristics (@  $T_c=22\pm 3C$ )**

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Response Spectrum	$\lambda$	—	400~1100			nm
Photosensitive diameter	$\varnothing$	—	800			$\mu$ m
Responsivity	$Re$	$\lambda=1064nm, \varphi_e=1\mu w, M=100$	30	36	—	A/W
Response time	$t_s$	$f=1MHz, RL=50\Omega, \lambda=1064nm$	—	2.0	—	ns
Dark Current	$I_D$	$M=100$	—	5.0	12.0	nA
Total capacitance	$C_{tot}$	$M=100, f=1MHz$	—	2.5	4.0	pF
Reverse Breakdown Voltage	$V_{BR}$	$I_R = 10\mu A$	350	—	460	V
Temperature coefficient of VBR	$\delta$	$T_c=-40^{\circ}C \sim 85^{\circ}C$	—	2.4	3.0	V/ $^{\circ}C$

## ❖ Die Dimensions

Parameter	Min.	Typ.	Max.	Unit	Notes
Die Width	1550	1560	1570	$\mu\text{m}$	
Die Length	1550	1560	1570	$\mu\text{m}$	
Thickness	110	120	130	$\mu\text{m}$	
R N metal	—	80	—	$\mu\text{m}$	Al metal
P metal	—				Al metal



## ❖ Introduction

The structure of Si avalanche photodiode, which can convert optical signal to current signal and multiply it internally, is planar and front illuminated with N electrode on the top and P electrode on the bottom.

Bonding force and temperature should be applied in a gradual fashion.